

SELECTIVE SOLDER

RECOMMENDED PROCESS PARAMETERS

SOLDER TEMPERATURE

Measure and verify regularly that the set solder temperature is stable.

Recommended: Check every 2 weeks.

PREHEATER

Measure and verify regularly that the set temperature profile on the top and bottom of the PCB is stable.

Recommended: Check every week or every time you change a product over.

FLUX

Check the Flux quality. Since only a small amount of Flux is used for selective soldering, make sure the Flux in the tank has not expired.

Make sure maintenance is done on the Spray Fluxer.

Make sure the Fluxer is spraying correctly.

Recommended: Should be checked every shift.

NOZZLE

Monitor wave height.

Recommended: Clean wettable nozzle 2 to 3 times per shift.

POSITION OF THE BOARD

Make sure the PCB orientation is always the same when loading the machine.

SELECTIVE SOLDER RECOMMENDED PROCESS PARAMETERS (cont.)

BOARD WARPING

A heavily warped board cannot be controlled by the selective soldering machine.
Make sure the board is as even as possible.
If necessary, use special solder fixtures.

LEAD LENGTH OF COMPONENTS

Sometimes the leads to be soldered are cut in different working/assembly steps. Since the lead length in selective soldering is very important, make sure that the leads are all the same length.

Recommended: Ideally all leads should be identical in length and less than 1.5mm.

N2 QUALITY

Always check the purity of the N2.

Recommended: N2 quality should be 5.1 (=99.999% N2).